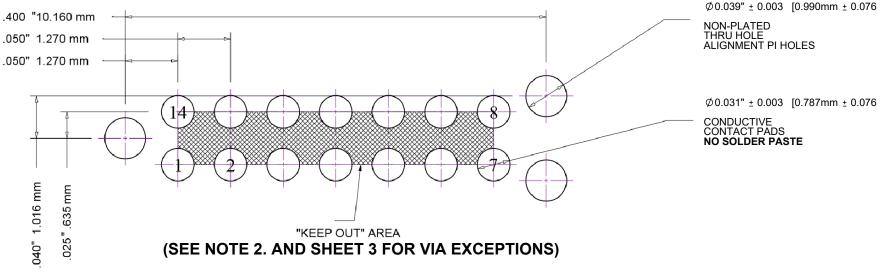
2 3 4 5 6 7 8 9 10 11 12 13 14 15 16 17 18 19 20 21 22 23 24 25 26

PCB LAYOUT NOTES:

1. No tracks or vias in the shaded "KEEP OUT" area.

2. No other track or signal within 0.020" of any contact pad.

- 3. Do not allow solder paste on the contact pads. It is essential to eliminate any hole in the solder paste-mask (solder stencil) layer. If this is not possible make the contact pads thru-hole with finished hole size of 0.012" or less.
- 4. To avoid ordering confusion, *please* specify DNL in your BOM the PCB footprint IS NOT A PHYSICAL PART.
- 5. The TC2070-CLIP board can attach to the three alignment pins from underneath the PCB to temporarrily retain the cable in place.

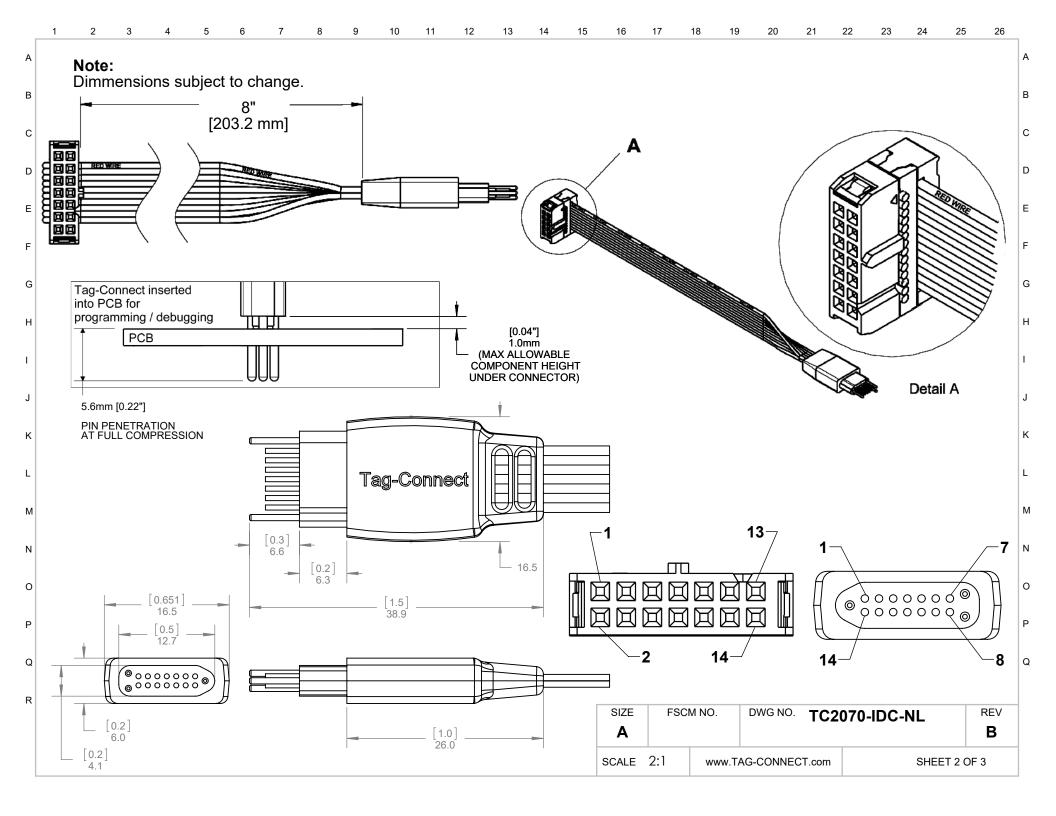


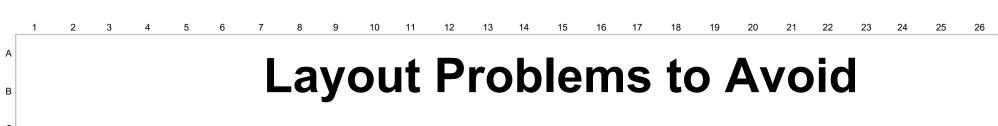
PCB TOP LAYER

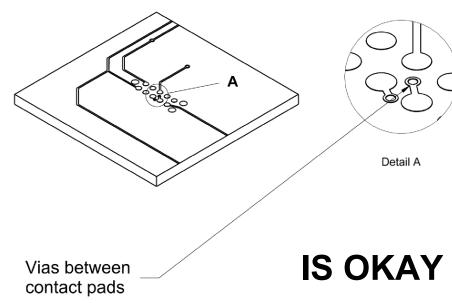
FOOTPRINT TO BE LABELED "TC2070-NL-FP" ON LAYOUT / BOM

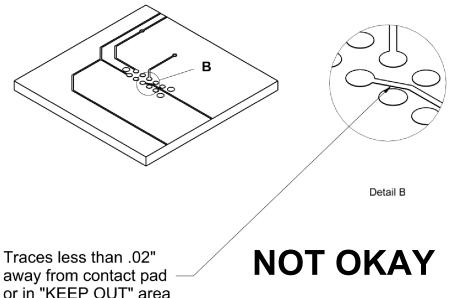
Use TC2070-FP (or TC2070-NL-FP) as the PCB "part" name – the cable must not appear on your BOM! Ensure the "part" in the PCB BOM is labelled as "Nothing to Purchase - Do Not Install" otherwise your CM's will try to buy one cable per PCB assembly!

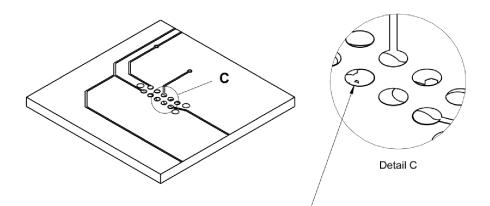
SIZE A	FSCM NO.		DWG NO. TC2070-IDC-NL		REV B
SCALE	1:5	www.T.	AG-CONNECT.com	SHEET 1 OF 3	











Do not deposit solder paste on contact pads. View Solder Paste Mask (Solder Stencil) layer in pad-stack and eliminate any hole.

Notes:

- 1) It IS OK to have a conductive via (not filled, not soldermasked) in the center of any of the pads so long as the finished hole is 0.012" or smaller.
- 2) It's NOT OK to have a via between two pads without 0.02" between the via and a pad of a different signal.
- 3) It IS OK to have a small via centered between four pads.

SIZE A	FSCM NO.		DWG NO. TC2070-IDC-NL		070-IDC-NL	REV B
SCALE	2:1	www.TAG-CONNECT.co			SHEET 3 OF 3	